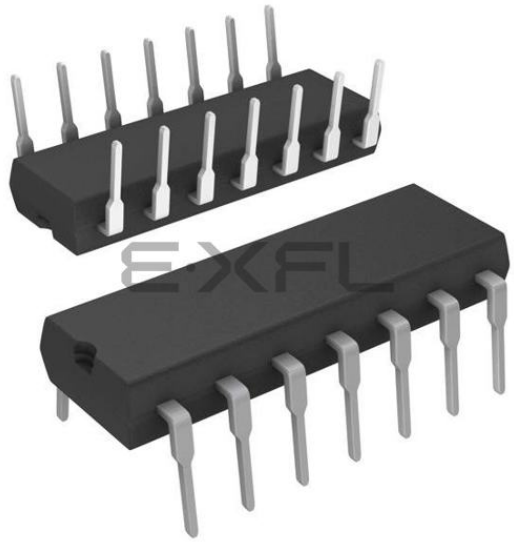

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	14-DIP (0.300", 7.62mm)
Supplier Device Package	14-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f684-i-p

14-Pin Diagram (PDIP, SOIC, TSSOP)

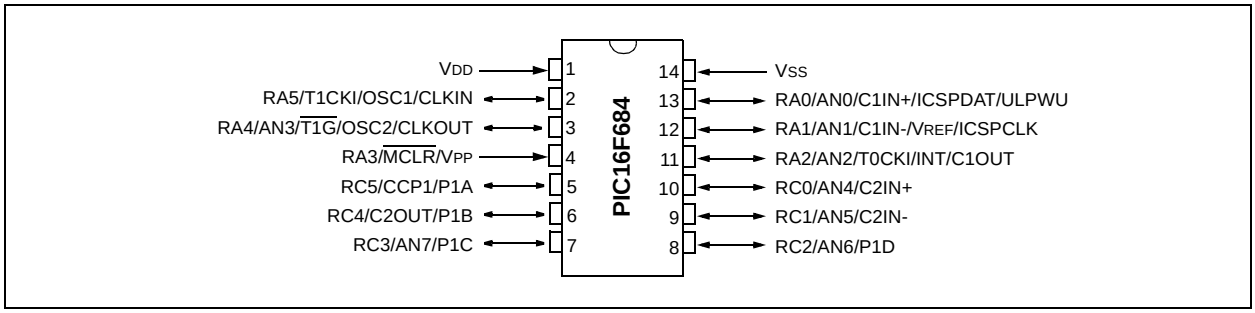


TABLE 1: DUAL IN-LINE PIN SUMMARY

I/O	Pin	Analog	Comparators	Timer	CCP	Interrupts	Pull-ups	Basic
RA0	13	AN0	C1IN+	—	—	IOC	Y	ICSPDAT/ULPWU
RA1	12	AN1/VREF	C1IN-	—	—	IOC	Y	ICSPCLK
RA2	11	AN2	C1OUT	T0CKI	—	INT/IOC	Y	—
RA3(1)	4	—	—	—	—	IOC	Y(2)	MCLR/VPP
RA4	3	AN3	—	T1G	—	IOC	Y	OSC2/CLKOUT
RA5	2	—	—	T1CKI	—	IOC	Y	OSC1/CLKIN
RC0	10	AN4	C2IN+	—	—	—	—	—
RC1	9	AN5	C2IN-	—	—	—	—	—
RC2	8	AN6	—	—	P1D	—	—	—
RC3	7	AN7	—	—	P1C	—	—	—
RC4	6	—	C2OUT	—	P1B	—	—	—
RC5	5	—	—	—	CCP1/P1A	—	—	—
—	1	—	—	—	—	—	—	VDD
—	14	—	—	—	—	—	—	VSS

Note 1: Input only.

2: Only when pin is configured for external MCLR.

16-Pin Diagram (QFN)

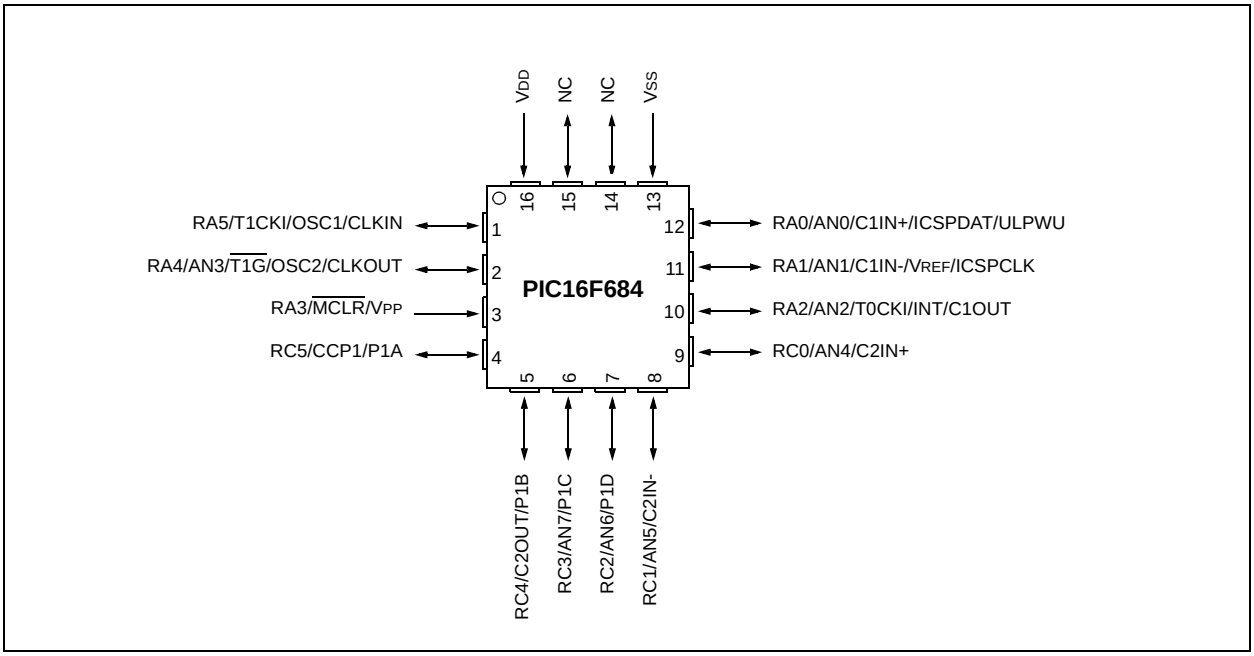


TABLE 2: QFN PIN SUMMARY

I/O	Pin	Analog	Comparators	Timers	CCP	Interrupts	Pull-ups	Basic
RA0	12	AN0	C1IN+	—	—	IOC	Y	ICSPDAT/ULPWU
RA1	11	AN1/VREF	C1IN-	—	—	IOC	Y	ICSPCLK
RA2	10	AN2	C1OUT	T0CKI	—	INT/IOC	Y	—
RA3(1)	3	—	—	—	—	IOC	Y(2)	MCLR/VPP
RA4	2	AN3	—	T1G	—	IOC	Y	OSC2/CLKOUT
RA5	1	—	—	T1CKI	—	IOC	Y	OSC1/CLKIN
RC0	9	AN4	C2IN+	—	—	—	—	—
RC1	8	AN5	C2IN-	—	—	—	—	—
RC2	7	AN6	—	—	P1D	—	—	—
RC3	6	AN7	—	—	P1C	—	—	—
RC4	5	—	C2OUT	—	P1B	—	—	—
RC5	4	—	—	—	CCP1/P1A	—	—	—
—	16	—	—	—	—	—	—	VDD
—	13	—	—	—	—	—	—	VSS

Note 1: Input only.

2: Only when pin is configured for external MCLR.

2.2.1 GENERAL PURPOSE REGISTER FILE

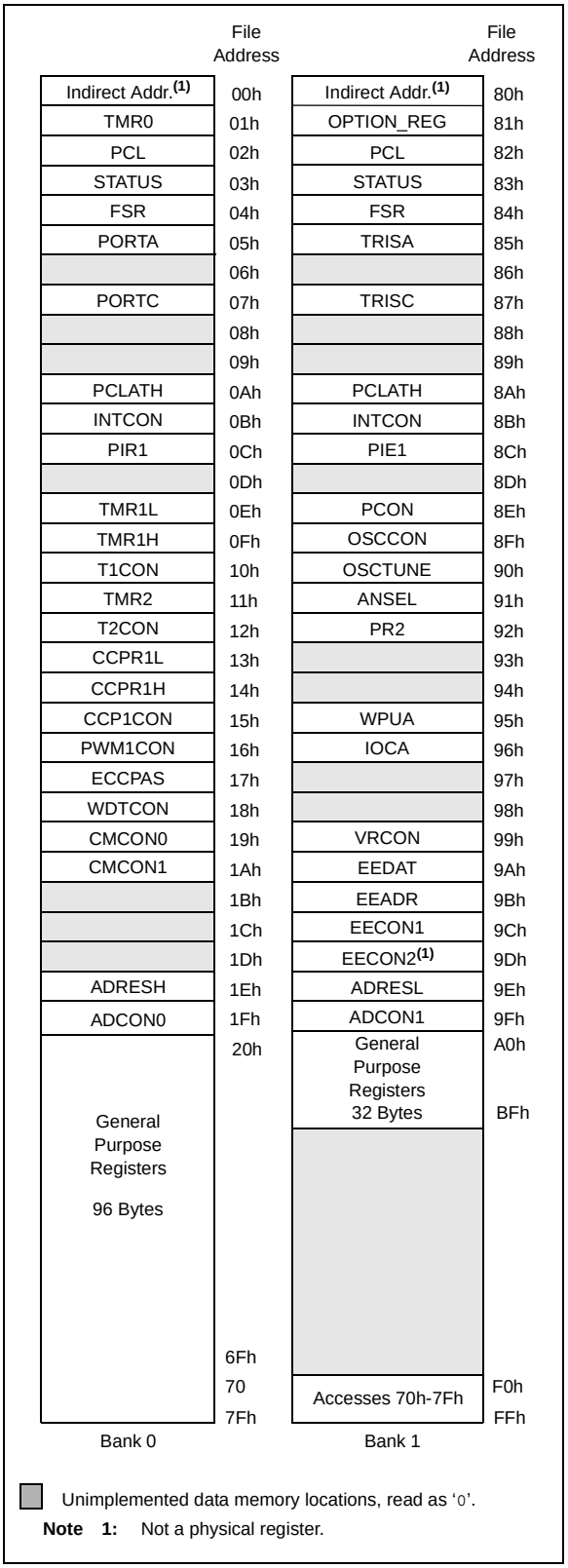
The register file is organized as 128 x 8 in the PIC16F684. Each register is accessed, either directly or indirectly, through the File Select Register (FSR) (see **Section 2.4 "Indirect Addressing, INDF and FSR Registers"**).

2.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions for controlling the desired operation of the device (see Table 2-1). These registers are static RAM.

The special registers can be classified into two sets: core and peripheral. The Special Function Registers associated with the "core" are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

FIGURE 2-2: DATA MEMORY MAP OF THE PIC16F684



Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

2.2.2.1 STATUS Register

The STATUS register, shown in Register 2-1, contains:

- the arithmetic status of the ALU
- the Reset status
- the bank select bits for data memory (SRAM)

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS`, will clear the upper three bits and set the Z bit. This leaves the STATUS register as `'000u u1uu'` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits, see **Section 13.0 "Instruction Set Summary"**.

Note 1:	Bits IRP and RP1 of the STATUS register are not used by the PIC16F684 and should be maintained as clear. Use of these bits is not recommended, since this may affect upward compatibility with future products.
2:	The C and DC bits operate as a $\overline{Borrow}$ and $\overline{Digit\ Borrow}$ out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

REGISTER 2-1: STATUS: STATUS REGISTER

Reserved	Reserved	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IRP:** This bit is reserved and should be maintained as '0'

bit 6 **RP1:** This bit is reserved and should be maintained as '0'

bit 5 **RP0:** Register Bank Select bit (used for direct addressing)
- 1 = Bank 1 (80h – FFh)
- 0 = Bank 0 (00h – 7Fh)

bit 4 **$\overline{TO}$:** Time-out bit
- 1 = After power-up, `CLRWDT` instruction or `SLEEP` instruction
- 0 = A WDT time-out occurred

bit 3 **$\overline{PD}$:** Power-down bit
- 1 = After power-up or by the `CLRWDT` instruction
- 0 = By execution of the `SLEEP` instruction

bit 2 **Z:** Zero bit
- 1 = The result of an arithmetic or logic operation is zero
- 0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{Borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions), For $\overline{Borrow}$, the polarity is reversed.
- 1 = A carry-out from the 4th low-order bit of the result occurred
- 0 = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{Borrow}$ bit(1) (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
- 1 = A carry-out from the Most Significant bit of the result occurred
- 0 = No carry-out from the Most Significant bit of the result occurred

Note 1: For $\overline{Borrow}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high-order or low-order bit of the source register.

4.2.5 PIN DESCRIPTIONS AND DIAGRAMS

Each PORTA pin is multiplexed with other functions. The pins and their combined functions are briefly described here. For specific information about individual functions such as the Comparator or the ADC, refer to the appropriate section in this data sheet.

4.2.5.1 RA0/AN0/C1IN+/ICSPDAT/ULPWU

Figure 4-1 shows the diagram for this pin. The RA0 pin is configurable to function as one of the following:

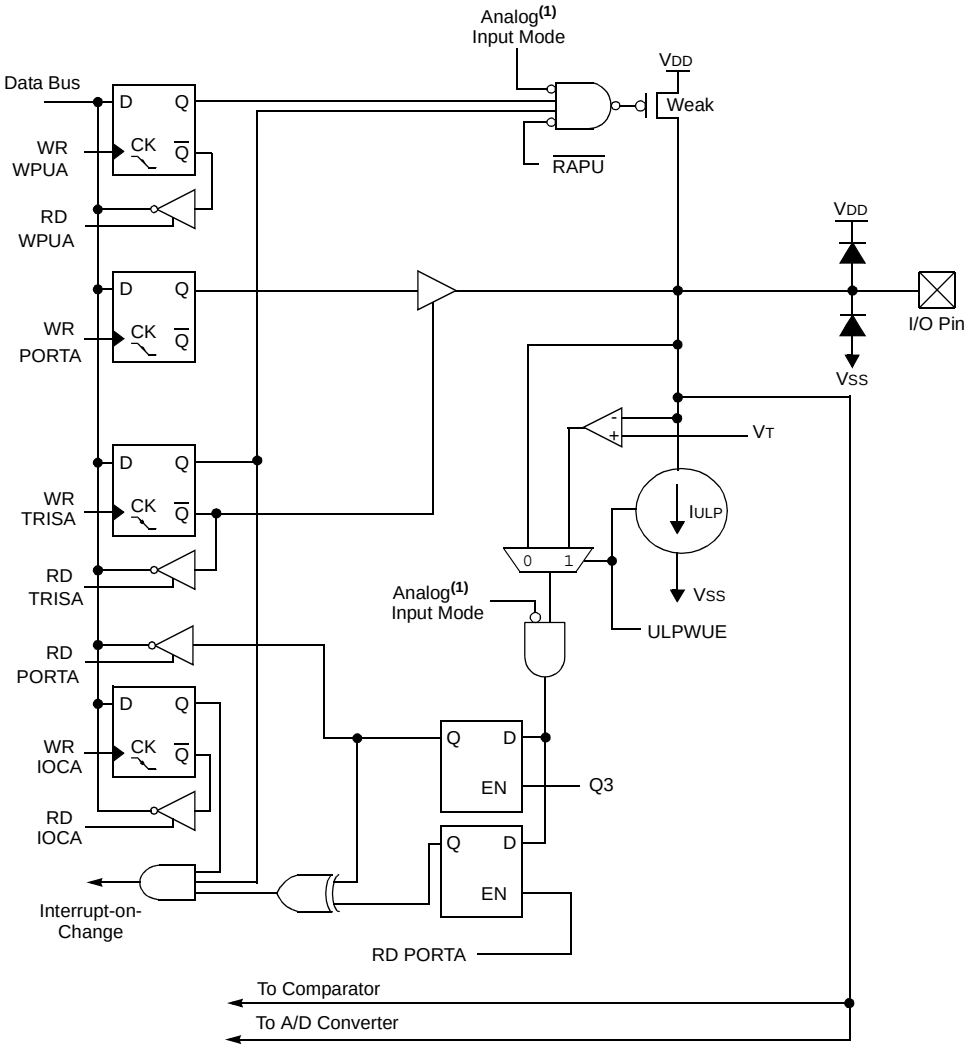
- a general purpose I/O
- an analog input for the ADC
- an analog non-inverting input to the comparator
- In-Circuit Serial Programming data
- an analog input for the Ultra Low-Power Wake-Up

4.2.5.2 RA1/AN1/C1IN-/VREF/ICSPCLK

Figure 4-2 shows the diagram for this pin. The RA1 pin is configurable to function as one of the following:

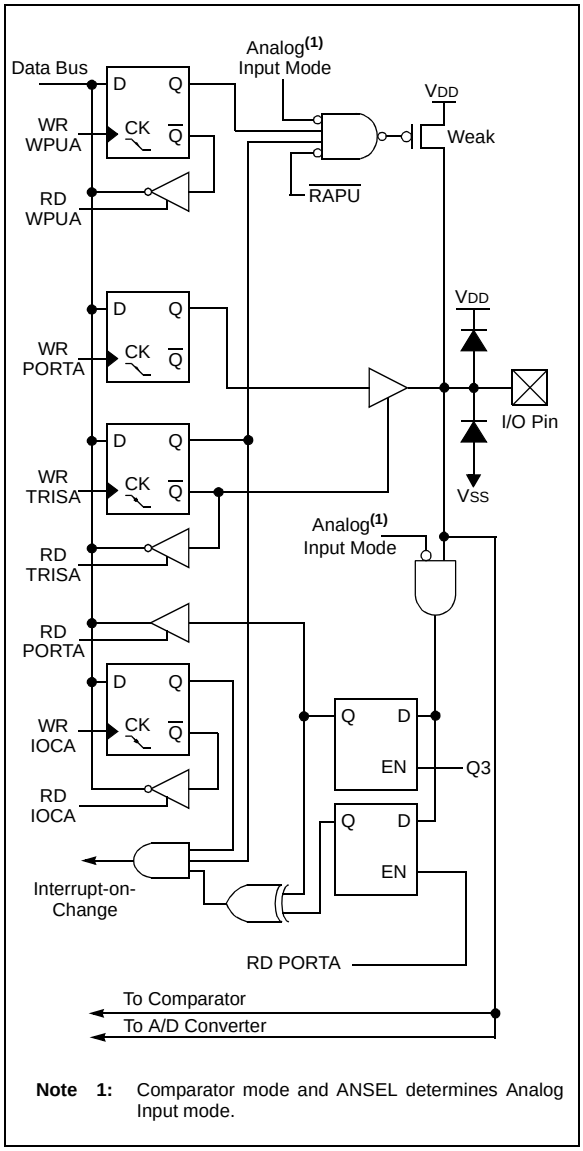
- a general purpose I/O
- an analog input for the ADC
- an analog inverting input to the comparator
- a voltage reference input for the ADC
- In-Circuit Serial Programming clock

FIGURE 4-1: BLOCK DIAGRAM OF RA0



Note 1: Comparator mode and ANSEL determines Analog Input mode.

FIGURE 4-2: BLOCK DIAGRAM OF RA1



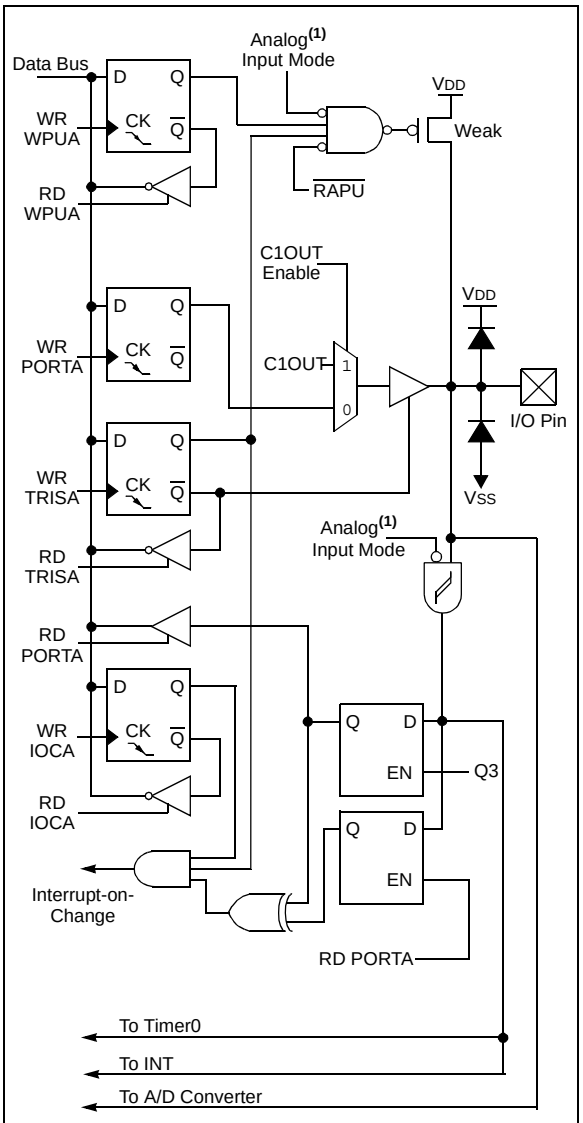
Note 1: Comparator mode and ANSEL determines Analog Input mode.

4.2.5.3 RA2/AN2/T0CKI/INT/C1OUT

Figure 4-3 shows the diagram for this pin. The RA2 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the ADC
- the clock input for TMR0
- an external edge triggered interrupt
- a digital output from Comparator 1

FIGURE 4-3: BLOCK DIAGRAM OF RA2



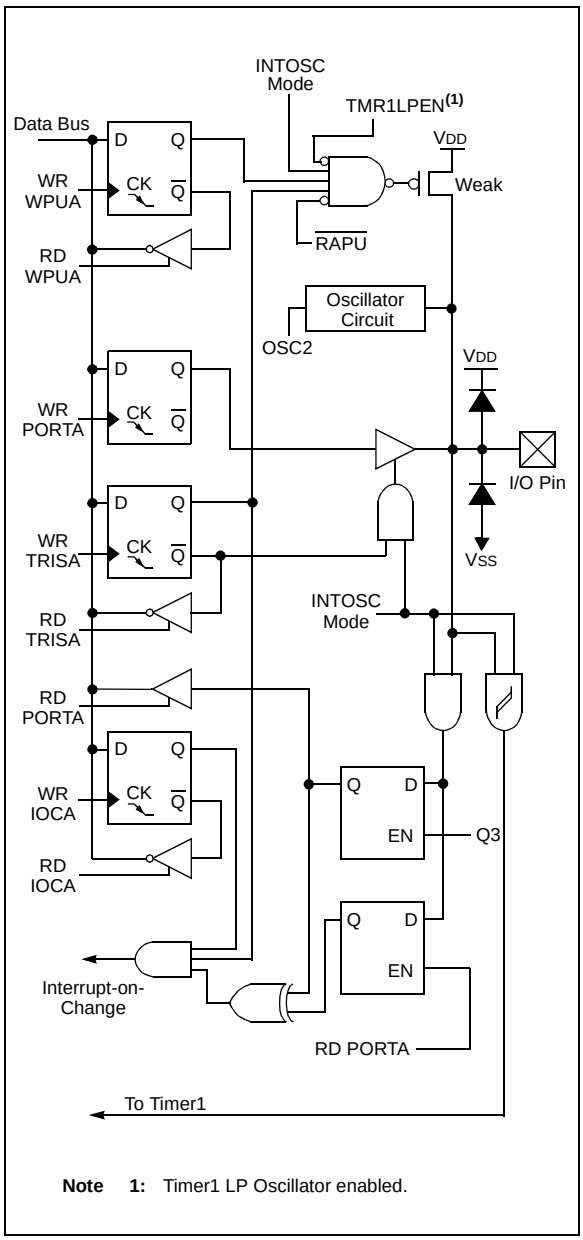
Note 1: Analog Input mode is generated by ANSEL.

4.2.5.6 RA5/T1CKI/OSC1/CLKIN

Figure 4-6 shows the diagram for this pin. The RA5 pin is configurable to function as one of the following:

- a general purpose I/O
- a Timer1 clock input
- a crystal/resonator connection
- a clock input

FIGURE 4-6: BLOCK DIAGRAM OF RA5



Note 1: Timer1 LP Oscillator enabled.

8.8 Comparator C2 Gating Timer1

This feature can be used to time the duration or interval of analog events. Clearing the T1GSS bit of the CMCON1 register will enable Timer1 to increment based on the output of Comparator C2. This requires that Timer1 is on and gating is enabled. See **Section 6.0 "Timer1 Module with Gate Control"** for details.

It is recommended to synchronize Comparator C2 with Timer1 by setting the C2SYNC bit when the comparator is used as the Timer1 gate source. This ensures Timer1 does not miss an increment if the comparator changes during an increment.

8.9 Synchronizing Comparator C2 Output to Timer1

The output of Comparator C2 can be synchronized with Timer1 by setting the C2SYNC bit of the CMCON1 register. When enabled, the comparator output is latched on the falling edge of the Timer1 clock source. If a prescaler is used with Timer1, the comparator output is latched after the prescaling function. To prevent a race condition, the comparator output is latched on the falling edge of the Timer1 clock source and Timer1 increments on the rising edge of its clock source. Reference the comparator block diagrams (Figure 8-2 and Figure 8-3) and the Timer1 Block Diagram (Figure 6-1) for more information.

REGISTER 8-2: CMCON1: COMPARATOR CONFIGURATION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0
—	—	—	—	—	—	T1GSS	C2SYNC
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **T1GSS:** Timer1 Gate Source Select bit(1)
- 1 = Timer1 gate source is $\overline{T1G}$ pin (pin should be configured as digital input)
- 0 = Timer1 gate source is Comparator C2 output

bit 0 **C2SYNC:** Comparator C2 Output Synchronization bit(2)
- 1 = Output is synchronized with falling edge of Timer1 clock
- 0 = Output is asynchronous

Note 1: Refer to **Section 6.6 "Timer1 Gate"**.
2: Refer to Figure 8-3.

10.5 Protection Against Spurious Write

There are conditions when the user may not want to write to the data EEPROM memory. To protect against spurious EEPROM writes, various mechanisms have been built in. On power-up, WREN is cleared. Also, the Power-up Timer (64 ms duration) prevents EEPROM write.

The write initiate sequence and the WREN bit together help prevent an accidental write during:

- Brown-out
- Power Glitch
- Software Malfunction

10.6 Data EEPROM Operation During Code-Protect

Data memory can be code-protected by programming the $\overline{\text{CPD}}$ bit in the Configuration Word register (Register 12-1) to '0'.

When the data memory is code-protected, the CPU is able to read and write data to the data EEPROM. It is recommended to code-protect the program memory when code-protecting data memory. This prevents anyone from programming zeroes over the existing code (which will execute as NOPs) to reach an added routine, programmed in unused program memory, which outputs the contents of data memory. Programming unused locations in program memory to '0' will also help prevent data memory code protection from becoming breached.

TABLE 10-1: SUMMARY OF ASSOCIATED DATA EEPROM REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 0000
PIR1	EEIF	ADIF	CCP1IF	C2IF	C1IF	OSFIF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	EEIE	ADIE	CCP1IE	C2IE	C1IE	OSFIE	TMR2IE	TMR1IE	0000 0000	0000 0000
EEDAT	EEDAT7	EEDAT6	EEDAT5	EEDAT4	EEDAT3	EEDAT2	EEDAT1	EEDAT0	0000 0000	0000 0000
EEADR	EEADR7	EEADR6	EEADR5	EEADR4	EEADR3	EEADR2	EEADR1	EEADR0	0000 0000	0000 0000
EECON1	—	—	—	—	WRERR	WREN	WR	RD	---- x000	---- q000
EECON2(1)	EEPROM Control Register 2								---- ----	---- ----

Legend: x = unknown, u = unchanged, – = unimplemented read as '0', q = value depends upon condition. Shaded cells are not used by the Data EEPROM module.

Note 1: EECON2 is not a physical register.

11.3.1 PWM PERIOD

The PWM period is specified by the PR2 register of Timer2. The PWM period can be calculated using the formula of Equation 11-1.

EQUATION 11-1: PWM PERIOD

$$PWM\ Period = [(PR2) + 1] \bullet 4 \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The CCP1 pin is set. (Exception: If the PWM duty cycle = 0%, the pin will not be set.)
- The PWM duty cycle is latched from CCPR1L into CCPR1H.

Note:	The Timer2 postscaler (see **Section 7.1 "Timer2 Operation"**) is not used in the determination of the PWM frequency.

11.3.2 PWM DUTY CYCLE

The PWM duty cycle is specified by writing a 10-bit value to multiple registers: CCPR1L register and CCP1<1:0> bits of the CCP1CON register. The CCPR1L contains the eight MSbs and the CCP1<1:0> bits of the CCP1CON register contain the two LSbs. CCPR1L and CCP1<1:0> bits of the CCP1CON register can be written to at any time. The duty cycle value is not latched into CCPR1H until after the period completes (i.e., a match between PR2 and TMR2 registers occurs). While using the PWM, the CCPR1H register is read-only.

Equation 11-2 is used to calculate the PWM pulse width.

Equation 11-3 is used to calculate the PWM duty cycle ratio.

EQUATION 11-2: PULSE WIDTH

$$Pulse\ Width = (CCPR1L:CCP1CON<5:4>) \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

EQUATION 11-3: DUTY CYCLE RATIO

$$Duty\ Cycle\ Ratio = \frac{(CCPR1L:CCP1CON<5:4>)}{4(PR2 + 1)}$$

The CCPR1H register and a 2-bit internal latch are used to double buffer the PWM duty cycle. This double buffering is essential for glitchless PWM operation.

The 8-bit timer TMR2 register is concatenated with either the 2-bit internal system clock (FOSC), or 2 bits of the prescaler, to create the 10-bit time base. The system clock is used if the Timer2 prescaler is set to 1:1.

When the 10-bit time base matches the CCPR1H and 2-bit latch, then the CCP1 pin is cleared (see Figure 11-3).

11.3.3 PWM RESOLUTION

The resolution determines the number of available duty cycles for a given period. For example, a 10-bit resolution will result in 1024 discrete duty cycles, whereas an 8-bit resolution will result in 256 discrete duty cycles.

The maximum PWM resolution is 10 bits when PR2 is 255. The resolution is a function of the PR2 register value as shown by Equation 11-4.

EQUATION 11-4: PWM RESOLUTION

$$Resolution = \frac{\log[4(PR2 + 1)]}{\log(2)}\ bits$$

Note:	If the pulse width value is greater than the period the assigned PWM pin(s) will remain unchanged.

TABLE 11-2: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 20 MHz)

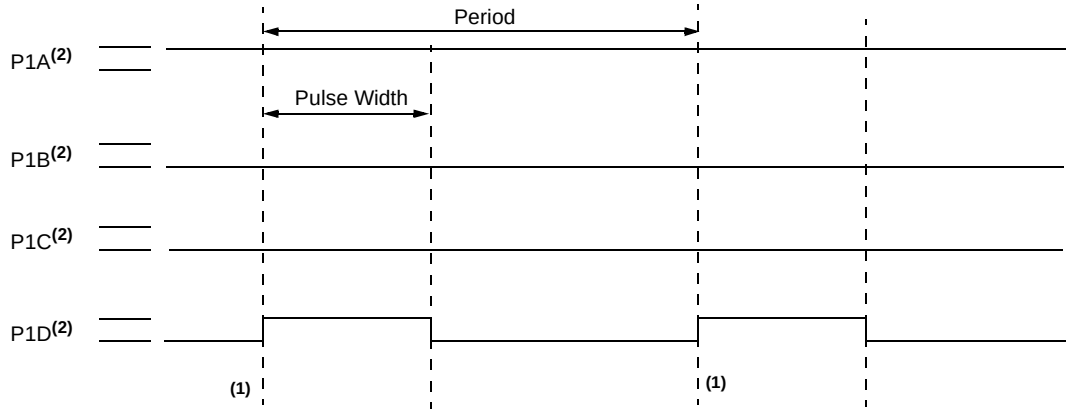
PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescale (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	6.6

TABLE 11-3: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 8 MHz)

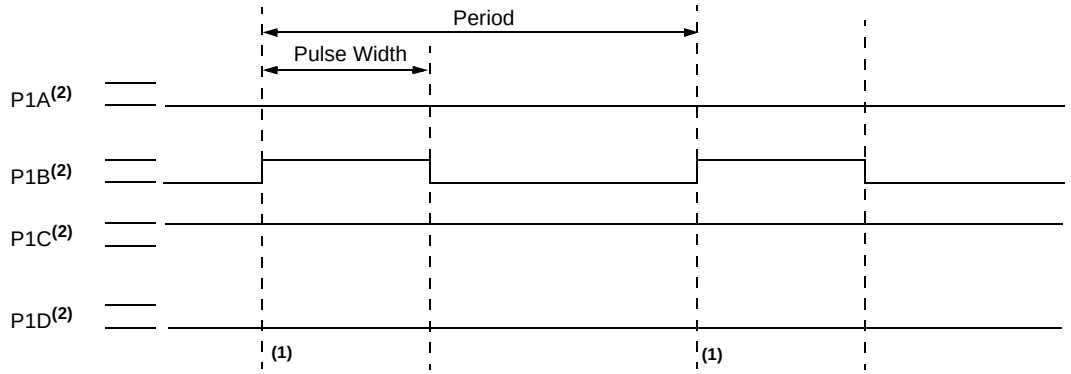
PWM Frequency	1.22 kHz	4.90 kHz	19.61 kHz	76.92 kHz	153.85 kHz	200.0 kHz
Timer Prescale (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0x65	0x65	0x65	0x19	0x0C	0x09
Maximum Resolution (bits)	8	8	8	6	5	5

FIGURE 11-11: EXAMPLE OF FULL-BRIDGE PWM OUTPUT

Forward Mode



Reverse Mode



Note 1: At this time, the TMR2 register is equal to the PR2 register.

2: Output signal is shown as active-high.

12.3.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in Reset until VDD has reached a high enough level for proper operation. To take advantage of the POR, simply connect the MCLR pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See **Section 15.0 "Electrical Specifications"** for details. If the BOR is enabled, the maximum rise time specification does not apply. The BOR circuitry will keep the device in Reset until VDD reaches VBOR (see **Section 12.3.4 "Brown-Out Reset (BOR)"**).

Note:	The POR circuit does not produce an internal Reset when VDD declines. To re-enable the POR, VDD must reach Vss for a minimum of 100 µs.

When the device starts normal operation (exits the Reset condition), device operating parameters (i.e., voltage, frequency, temperature, etc.) must be met to ensure proper operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Note AN607, *"Power-up Trouble Shooting"* (DS00607).

12.3.2 MCLR

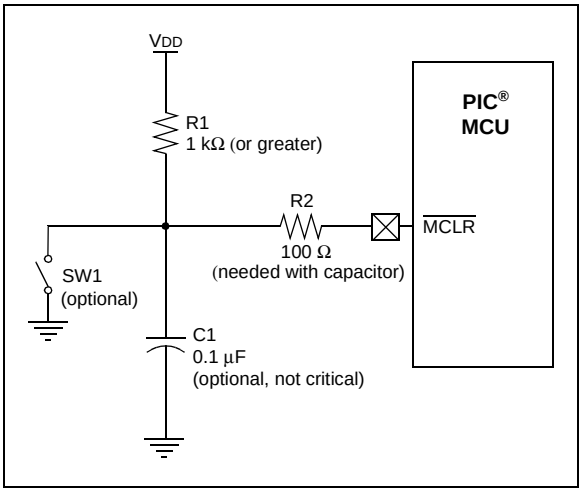
PIC16F684 has a noise filter in the MCLR Reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive MCLR pin low.

Voltages applied to the MCLR pin that exceed its specification can result in both MCLR Resets and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the MCLR pin no longer be tied directly to VDD. The use of an RC network, as shown in Figure 12-2, is suggested.

An internal MCLR option is enabled by clearing the MCLRE bit in the Configuration Word register. When MCLRE = 0, the Reset signal to the chip is generated internally. When the MCLRE = 1, the RA3/MCLR pin becomes an external Reset input. In this mode, the RA3/MCLR pin has a weak pull-up to VDD.

FIGURE 12-2: RECOMMENDED MCLR CIRCUIT



12.3.3 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 64 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates from the 31 kHz LFINTOSC oscillator. For more information, see **Section 3.5 "Internal Clock Modes"**. The chip is kept in Reset as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A Configuration bit, PWRTE, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should be enabled when Brown-out Reset is enabled, although it is not required.

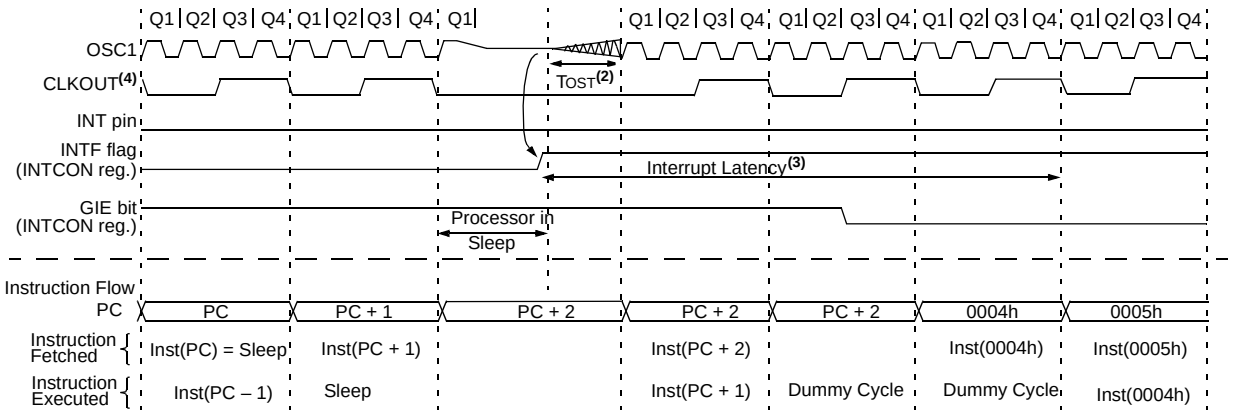
The Power-up Timer delay will varies from chip-to-chip due to:

- VDD variation
- Temperature variation
- Process variation

See DC parameters for details (**Section 15.0 "Electrical Specifications"**).

Note:	Voltage spikes below VSS at the MCLR pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a "low" level to the MCLR pin, rather than pulling this pin directly to VSS.

FIGURE 12-10: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS or LP Oscillator mode assumed.

2: TOST = 1024 TOSC (drawing not to scale). This delay does not apply to EC, INTOSC and RC Oscillator modes.

3: GIE = '1' assumed. In this case after wake-up, the processor jumps to 0004h. If GIE = '0', execution will continue in-line.

4: CLKOUT is not available in XT, HS, LP or EC Oscillator modes, but shown here for timing reference.

12.8 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out using ICSP™ for verification purposes.

Note:	The entire data EEPROM and Flash program memory will be erased when the code protection is turned off. See the "PIC12F6XX/16F6XX *Memory Programming Specification"* (DS41204) for more information.

12.9 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution but are readable and writable during Program/Verify mode. Only the Least Significant 7 bits of the ID locations are used.

15.1 DC Characteristics: PIC16F684-I (Industrial) PIC16F684-E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**	2.0	—	5.5	V	FOSC < = 8 MHz: HFINTOSC, EC
D001			2.0	—	5.5	V	FOSC < = 4 MHz
D001C			3.0	—	5.5	V	FOSC < = 10 MHz
D001D			4.5	—	5.5	V	FOSC < = 20 MHz
D002*	VDR	**RAM Data Retention Voltage(1)**	1.5	—	—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See **Section 12.3.1 "Power-On Reset (POR)"** for details.
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 12.3.1 "Power-On Reset (POR)"** for details.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

15.2 DC Characteristics: PIC16F684-I (Industrial) PIC16F684-E (Extended)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min	Typ†	Max	Units	Conditions	
						VDD	Note
D010	**Supply Current (IDD)(1, 2)**	—	11	16	µA	2.0	FOSC = 32 kHz LP Oscillator mode
		—	18	28	µA	3.0	
		—	35	54	µA	5.0	
D011*		—	140	240	µA	2.0	FOSC = 1 MHz XT Oscillator mode
		—	220	380	µA	3.0	
		—	380	550	µA	5.0	
D012		—	260	360	µA	2.0	FOSC = 4 MHz XT Oscillator mode
		—	420	650	µA	3.0	
		—	0.8	1.1	mA	5.0	
D013*		—	130	220	µA	2.0	FOSC = 1 MHz EC Oscillator mode
		—	215	360	µA	3.0	
		—	360	520	µA	5.0	
D014		—	220	340	µA	2.0	FOSC = 4 MHz EC Oscillator mode
		—	375	550	µA	3.0	
		—	0.65	1.0	mA	5.0	
D015		—	8	20	µA	2.0	FOSC = 31 kHz LFINTOSC mode
		—	16	40	µA	3.0	
		—	31	65	µA	5.0	
D016*		—	340	450	µA	2.0	FOSC = 4 MHz HFINTOSC mode
		—	500	700	µA	3.0	
		—	0.8	1.2	mA	5.0	
D017		—	410	650	µA	2.0	FOSC = 8 MHz HFINTOSC mode
		—	700	950	µA	3.0	
		—	1.30	1.65	mA	5.0	
D018		—	230	400	µA	2.0	FOSC = 4 MHz EXTRC mode(3)
		—	400	680	µA	3.0	
		—	0.63	1.1	mA	5.0	
D019		—	2.6	3.25	mA	4.5	FOSC = 20 MHz HS Oscillator mode
		—	2.8	3.35	mA	5.0	

* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.

TABLE 15-2: OSCILLATOR PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym**	**Characteristic**	**Freq Tolerance**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
OS06	TWARM	Internal Oscillator Switch when running(3)	—	—	—	2	TOSC	Slowest clock
OS07	TSC	Fail-Safe Sample Clock Period(1)	—	—	21	—	ms	LFINTOSC/64
OS08	HFOSC	Internal Calibrated HFINTOSC Frequency(2)	±1%	7.92	8.0	8.08	MHz	VDD = 3.5V, 25°C
			±2%	7.84	8.0	8.16	MHz	2.5V ≤ VDD ≤ 5.5V, 0°C ≤ TA ≤ +85°C
			±5%	7.60	8.0	8.40	MHz	2.0V ≤ VDD ≤ 5.5V, -40°C ≤ TA ≤ +85°C (Ind.), -40°C ≤ TA ≤ +125°C (Ext.)
OS09*	LFOSC	Internal Uncalibrated LFINTOSC Frequency	—	15	31	45	kHz	
OS10*	TIOSC ST	HFINTOSC Oscillator Wake-up from Sleep Start-up Time	—	5.5	12	24	µs	VDD = 2.0V, -40°C to +85°C
			—	3.5	7	14	µs	VDD = 3.0V, -40°C to +85°C
			—	3	6	11	µs	VDD = 5.0V, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at 'min' values with an external clock applied to the OSC1 pin. When an external clock input is used, the 'max' cycle time limit is 'DC' (no clock) for all devices.

2: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

3: By design.

TABLE 15-7: COMPARATOR SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym**	**Characteristics**		**Min**	**Typ†**	**Max**	**Units**	**Comments**
CM01	VOS	Input Offset Voltage		—	± 5.0	± 10	mV	(VDD - 1.5)/2
CM02	VCM	Input Common Mode Voltage		0	—	VDD – 1.5	V	
CM03*	CMRR	Common Mode Rejection Ratio		+55	—	—	dB	
CM04*	TRT	Response Time	Falling	—	150	600	ns	**(NOTE 1)**
			Rising	—	200	1000	ns	
CM05*	TMC2COV	Comparator Mode Change to Output Valid		—	—	10	µs	

* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Response time is measured with one comparator input at (VDD - 1.5)/2 - 100 mV to (VDD - 1.5)/2 + 20 mV.

TABLE 15-8: COMPARATOR VOLTAGE REFERENCE (CVREF) SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristics**	**Min**	**Typ†**	**Max**	**Units**	**Comments**
CV01*	CLSB	Step Size(2)	— —	VDD/24 VDD/32	— —	V V	Low Range (VRR = 1) High Range (VRR = 0)
CV02*	CACC	Absolute Accuracy	— —	— —	± 1/2 ± 1/2	LSb LSb	Low Range (VRR = 1) High Range (VRR = 0)
CV03*	CR	Unit Resistor Value (R)	—	2k	—	Ω	
CV04*	CST	Settling Time(1)	—	—	10	µs	

* These parameters are characterized but not tested.

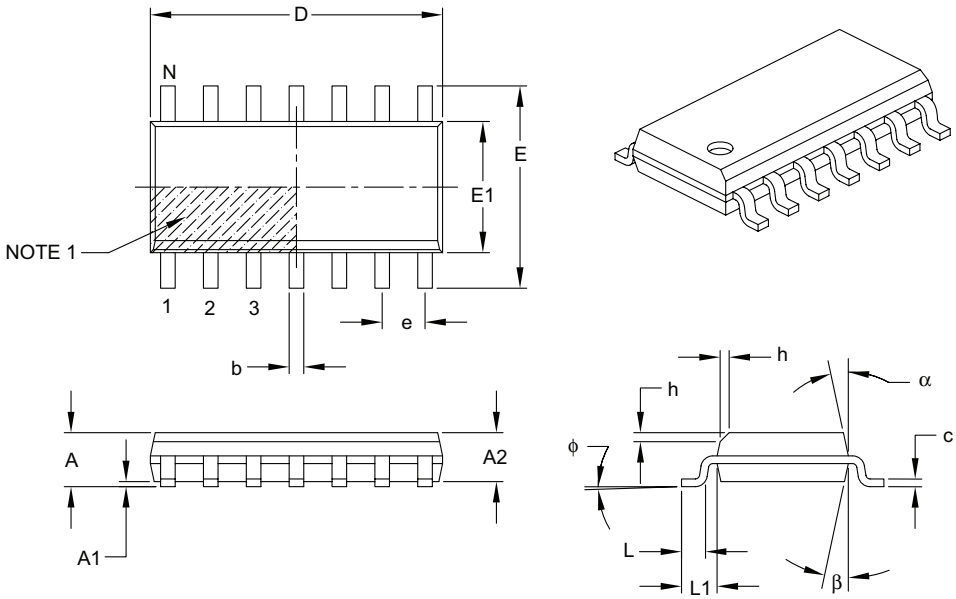
† Data in 'Typ' column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Settling time measured while VRR = 1 and VR<3:0> transitions from '0000' to '1111'.

2: See **Section 8.10 "Comparator Voltage Reference"** for more information.

14-Lead Plastic Small Outline (SL or OD) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		1.27 BSC	
Overall Height	A	–	–	1.75
Molded Package Thickness	A2	1.25	–	–
Standoff §	A1	0.10	–	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (optional)	h	0.25	–	0.50
Foot Length	L	0.40	–	1.27
Footprint	L1		1.04 REF	
Foot Angle	φ	0°	–	8°
Lead Thickness	c	0.17	–	0.25
Lead Width	b	0.31	–	0.51
Mold Draft Angle Top	α	5°	–	15°
Mold Draft Angle Bottom	β	5°	–	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

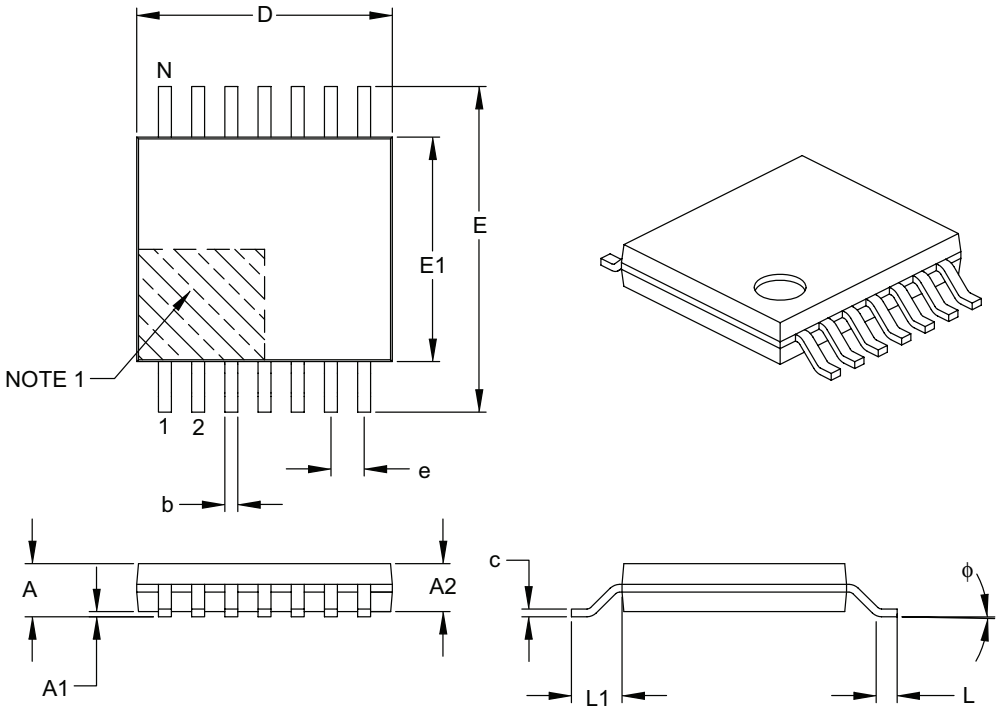
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-065B

14-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	–	0.15
Overall Width	E		6.40 BSC	
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	4.90	5.00	5.10
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	–	8°
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.19	–	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-087B